

A Study of the Metal/2D Semiconductor Contacts

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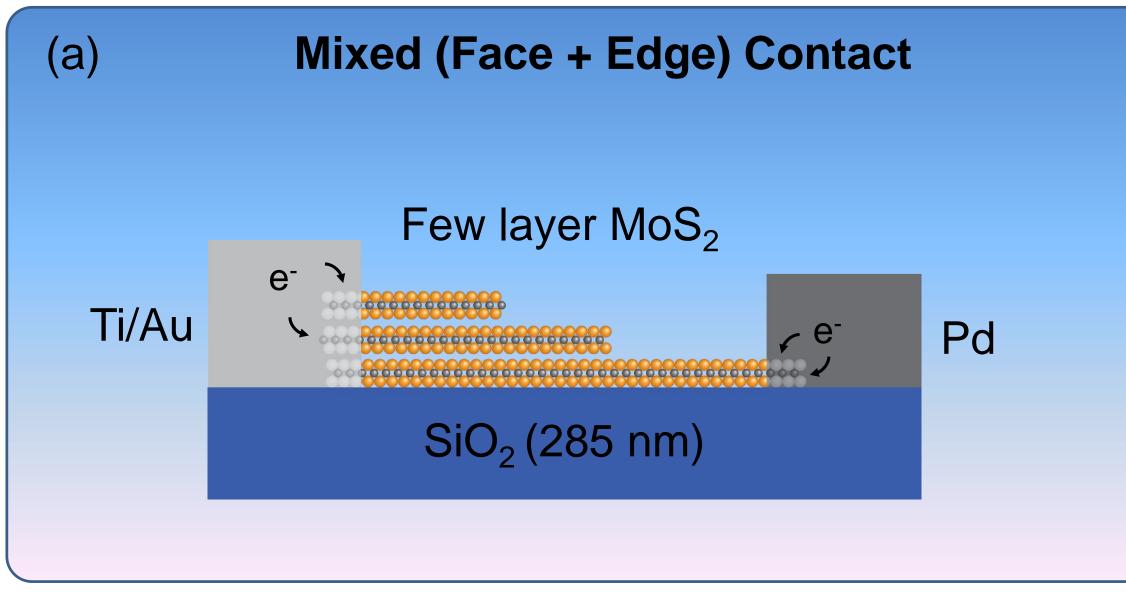
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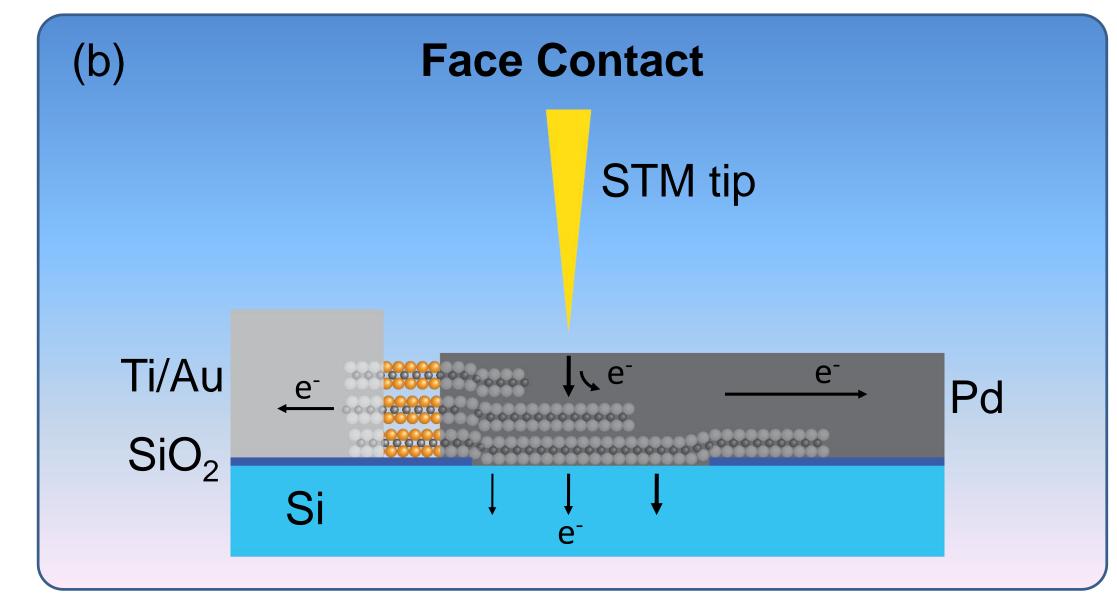
Introduction

Two dimensional (2D) semiconductors based on transition metal dichalcogenides (TMDCs) such as MoS_2 , $MoSe_2$, WS_2 and WSe_2 are promising materials for use in next generation electronics due to the presence of a bandgap in these materials and their tuneable electronic and optical properties. One of the major challenges in current research is to understand the nature of the metal/2D semiconductor contacts as the charge injection *into* and *through* the little understood interfaces are limiting the performance of these devices.^{1,2} In this poster, we present our strategy for investigating the Pd/MoS₂ Schottky interface using ballistic electron emission microscopy (BEEM) and explain its merit as a model system for understanding the metal/2D semiconductor interface.

Experimental Design

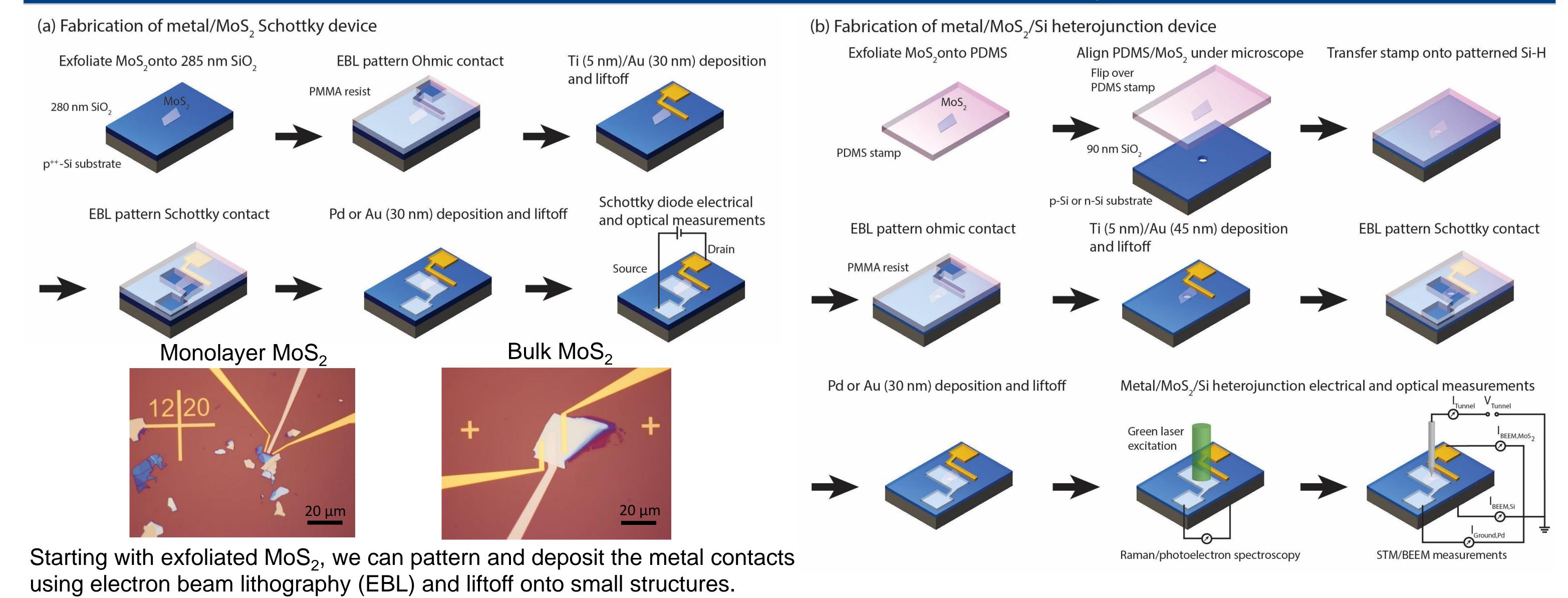
A fundamental problem in the understanding of the metal/2D semiconductor interface arises due to the anisotropy of the in-plane and out-of-plane electrical conductivity of the 2D semiconductor. The in-plane conductivity is typically two orders of magnitude higher than the out-of-plane conduction which may severely affect the charge transport into the 2D semiconductor. We propose two devices to study the mixed and face contacts of the metal/MoS₂ contact. (a) the Pd/MoS₂ Schottky junction and (b) the Pd/MoS₂/Si heterojunction.



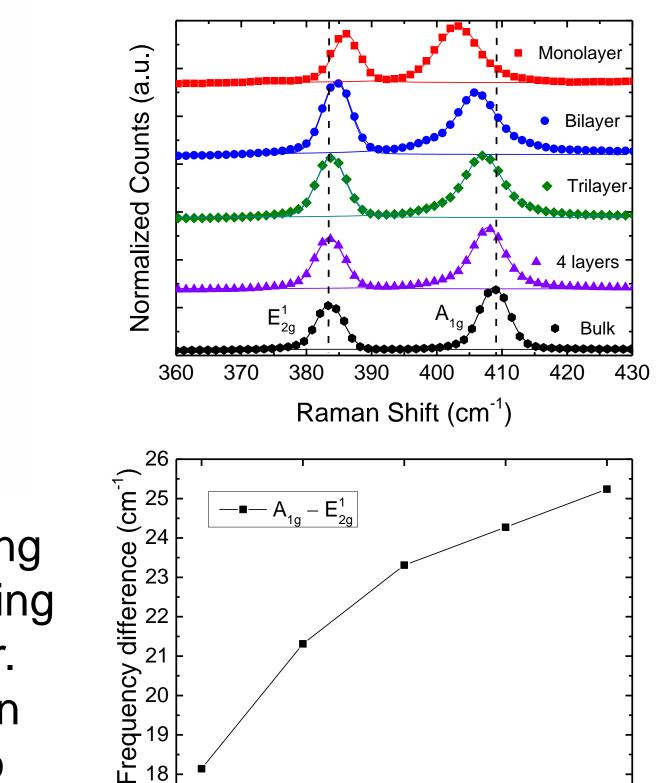


To study the mixed contact, we will use macroscopic electrical measurements such as temperature dependent current-voltage measurements (*I-V-T*). To study the face contact, we will use ballistic electrons from the STM tip to probe the buried metal/MoS₂ contact in a 4-probe ultra-high vacuum scanning tunneling microscope (UHV-STM) system set up in ballistic electron emission microscopy (BEEM) configuration.³

Device Fabrication: Metal/2D Semiconductor Schottky Diode



Raman Spectroscopy



2

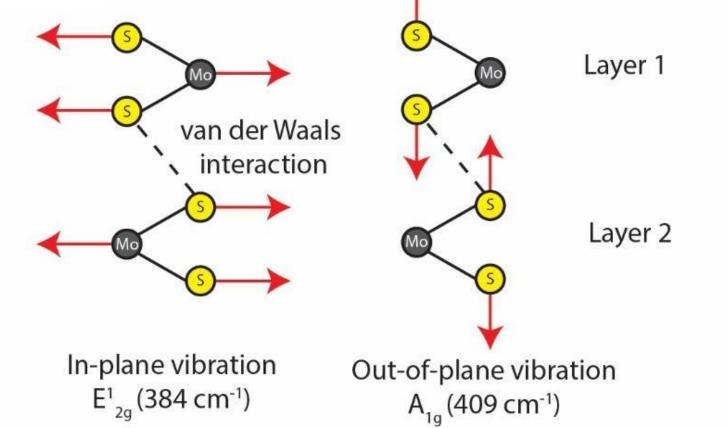
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Number of Layers

bulk

Conclusion and Outlook

We have presented our strategy to study the metal/2D semiconductor edge or face contacts by fabricating 2 types of metal/2D semiconductor devices and measuring them using conventional *I-V-T* measurements and ballistic electron emission microscopy. We expect to see a layer dependence charge injection efficiency into MoS_2 using the face contact. Fabrication of the metal/2D-semiconductor Schottky and heterojunction device are currently in progress.



 E_{2g}^{1} mode hardens due to increasing long range electrostatic forces as the screening effect decreases down to the monolayer. A_{1g} mode softens due to decreasing van der Waals forces as MoS₂ thins down to the monolayer.

Acknowledgements

We acknowledge funding from the National Research Foundation (NRF), Prime Minister's Office, Singapore under its medium sized center program (CA2DM) and project funding from IMRE for supporting this research.

References

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